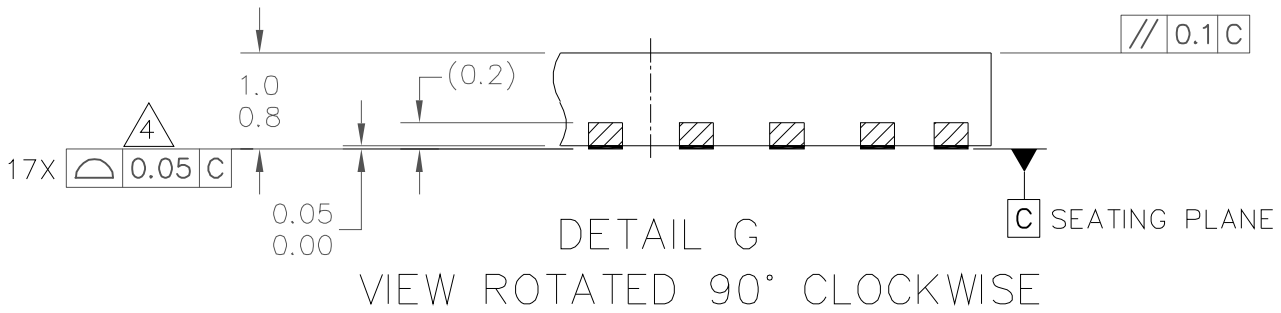


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TITLE: DFN, THERMALLY ENHANCED 4 X 6 X 0.9, 0.8 & 0.65 PITCH, 16 TERMINAL	DOCUMENT NO: 98ASA00868D REV: B	
	STANDARD: NON-JEDEC	
	SOT1862-1 27 JUL 2016	



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	STANDARD: NON-JEDEC	
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NOTES:

1. DIMENSIONING & TOLERANCING CONFIRM TO ASME Y14.5M-1994.

2. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

3. THIS DIMENSION APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 MM AND 0.30 MM FROM TERMINAL TIP.

4. COPLANARITY APPLIES TO THE EXPOSED HEAT SLUG AS WELL AS THE TERMINALS.

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